

CALL FOR PARTICIPATION

IEEE TTM is a unique event for industry leaders, academics and decision making government officials who direct R&D activities, plan research programs or manage portfolios of research activities. This is the first ever organized Symposium of future technologies and will cover in a tutorial way a selected set of potentially high impact emerging technologies, their current state of maturity and scenarios for the future.

The Symposium brings world renowned experts to discuss the evolutionary and revolutionary advances in technology landscapes as we look forward to 2020. All the presentations in this Symposium are given by invited World leading experts. The Symposium is structured to facilitate informal discussions among the participants and speakers. As the number of participants will be kept relatively small, this Symposium provides an excellent opportunity for informal interaction between the attendees and senior business leaders and world-renowned innovators. At the conclusion of the formal Symposium there will be an in depth session on the state of Cloud Computing. The Symposium will also provide the opportunity to visit some leading Hong Kong and Chinese research institutes and industries.

Please visit the TTM Symposium web site for more information:

<http://www.techbeyond2020.ust.hk/about.html>

Plenary Topics and Panel:

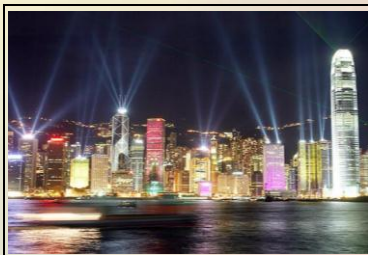
- China's Path to Technology Leadership
- Impact of Technology on Environment
- Smart Grid
- Display Technologies
- Corporate R&D Leaders' Panel

General Sessions:

- Advances in Biomedical Engineering
- Carbon Nanostructures and Conducting Polymers in Electronics
- Cloud Computing
- Digital Content at Home (Displays, Connectivity, Usability, etc.)
- E-Health
- Energy Harvesting and Storage (batteries, super capacitors)
- Future Directions in Wireless
- Future Mobile Services
- Future of Silicon-based Microelectronics
- Internet of Things

Keynote Speakers:

- *George Arnold*, National Coordinator for Smart Grid Interoperability, NIST, USA
- *Tony Chan*, President, Hong Kong University of Science and Technology, HK
- *Nobuhiro Endo*, CEO, NEC Corporation, Japan
- *Hoi Sing Kwok*, Chair Professor, ECE Department, HKUST, HK
- *Hequan Wu*, Former Vice-President, Chinese Academy of Engineering
- *Tomonori Aoyama*, Professor, ICE Department, The University of Tokyo, Japan
- *Micheal Austin*, Vice President, BYD America, USA
- *Hugh Bradlow*, Chief Technology Officer, Telstra, Australia
- *Ralph Etienne Cummings*, Professor, Whiting School of Engineering, John Hopkins University, USA
- *Jan Färjh*, Head of Ericsson research, Sweden
- *Masahiro Fujita*, President of System Technologies Laboratories, Sony Corporation, Japan
- *Peter Hartwell*, Distinguished Technologist, Hewlett-Packard Company, USA
- *Yongmin Kim*, Professor, EE Department, University of Washington, USA
- *Young Hee Lee*, Professor, Department of Physics, Sungkyunkwan University, Korea
- *Wouter Leibbrandt*, Manager, Advanced Systems Lab, NXP Semiconductors, Netherlands
- *Teck Seng Low*, Managing Director, A*STAR, Singapore
- *Rico Malvar*, Chief Scientist of Microsoft Research, USA
- *Pierre Mars*, Vice President, Applications Engineering, CAP-XX, Australia
- *Ada Poon*, Professor, EE Department, Stanford University, USA
- *Shigeru Sasaki*, Senior Vice President, Fujitsu Laboratories Ltd., Japan
- *Ghavam Shahidi*, IBM Fellow, Director of Silicon Tech., IBM Watson Research Ctr., USA
- *Henning Sirringhaus*, Hitachi Professor of Electron Device Physics, University of Cambridge, UK
- *Joe Weinman*, Worldwide Lead, Comm., Media, and Entertainment Ind. Sol., HP, USA
- *Philipp Zhang*, Chief Scientist, Huawei Technologies co., Ltd., China



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